

[54] SEMICONDUCTOR HOUSING

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[73] Assignee: Motorola, Inc., Schaumburg, Ill.

[\*\*] Term: 14 Years

[21] Appl. No.: 649,081

[22] Filed: Sep. 10, 1984

[52] U.S. Cl. .... D13/99; D13/41

[58] Field of Search ..... D13/40, 41, 99;  
361/394, 395, 399, 400, 331; 174/52 R, 52 PE,  
52 S; 357/70, 72, 74

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Primary Examiner—Susan J. Lucas

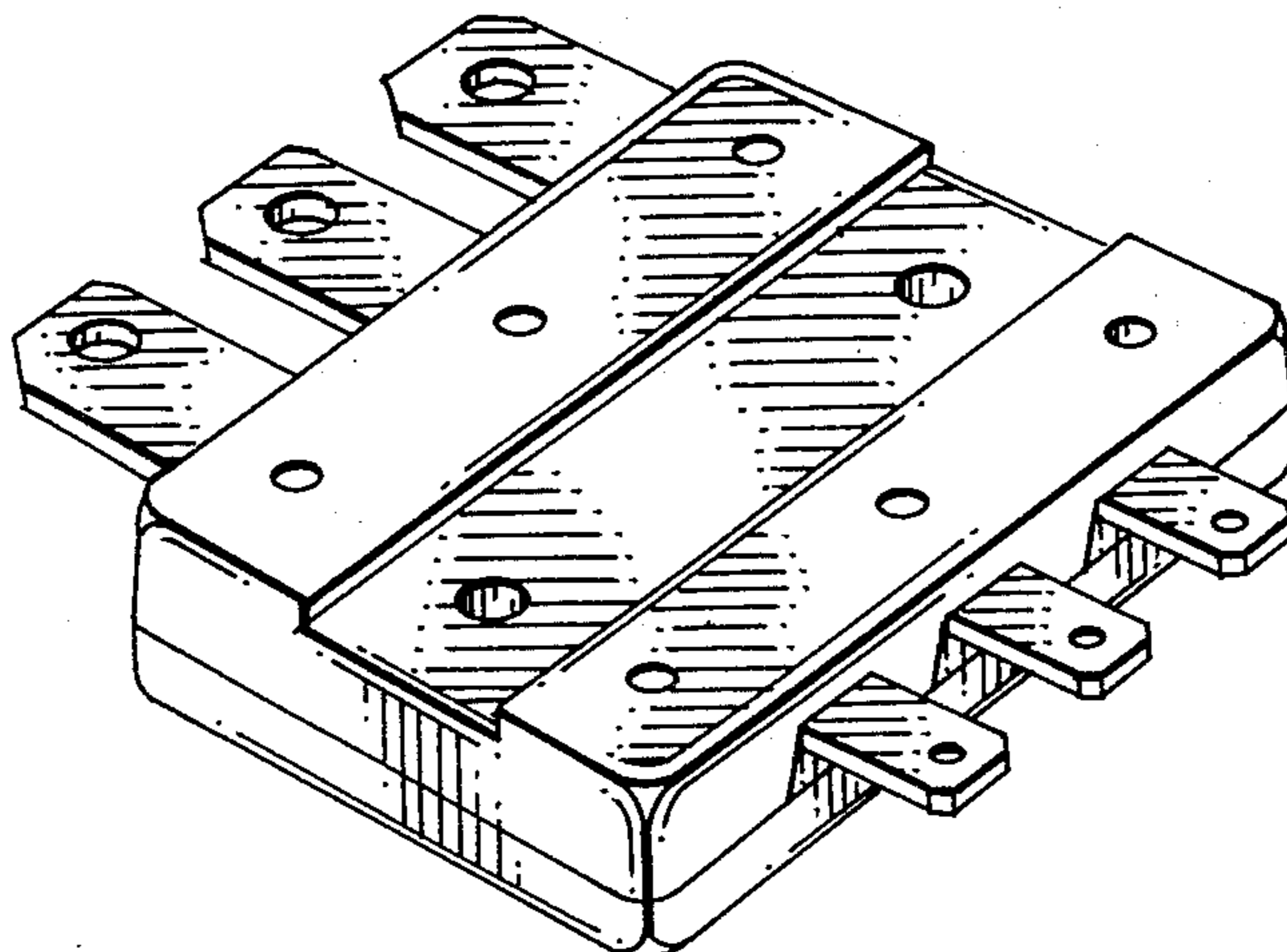
Attorney, Agent, or Firm—Robert Handy

[57] CLAIM

The ornamental design for a semiconductor housing, as shown and described.

DESCRIPTION

FIG. 1 is a right side, top and front perspective view of a semiconductor housing showing my new design; FIG. 2 is a top plan view thereof on a reduced scale; FIG. 3 is a bottom plan view thereof on a reduced scale; FIG. 4 is a left side elevational view thereof on a reduced scale; FIG. 5 is a right side elevational view thereof on a reduced scale; FIG. 6 is a front elevational view thereof on a reduced scale; FIG. 7 is a rear elevational view thereof on a reduced scale; FIG. 8 is a top plan view of second embodiment of my new design, the second embodiment being identical to the first except for the number of leads on the right hand side; FIG. 9 is a bottom plan view thereof; FIG. 10 is a top plan view of a third embodiment of my new design, the third design being identical to the first embodiment except for the shape of the two leads on the left hand side; FIG. 11 is a bottom plan view thereof; FIG. 12 is a right side, top and front perspective view of a fourth embodiment of my new design; FIG. 13 is a top plan view thereof on a reduced scale; FIG. 14 is a front elevational view thereof on a reduced scale; FIG. 15 is a left side elevational view thereof on a reduced scale; FIG. 16 is a right side, top and front perspective view of a fifth embodiment of my new design, the fifth embodiment being identical to the first embodiment except for the flat top surface; FIG. 17 is a right side, top and front perspective view of a sixth embodiment of my new design; FIG. 18 is a top plan view thereof on a reduced scale; FIG. 19 is a bottom plan view thereof on a reduced scale; FIG. 20 is a left side elevational view thereof on a reduced scale; FIG. 21 is a right side elevational view thereof on a reduced scale.



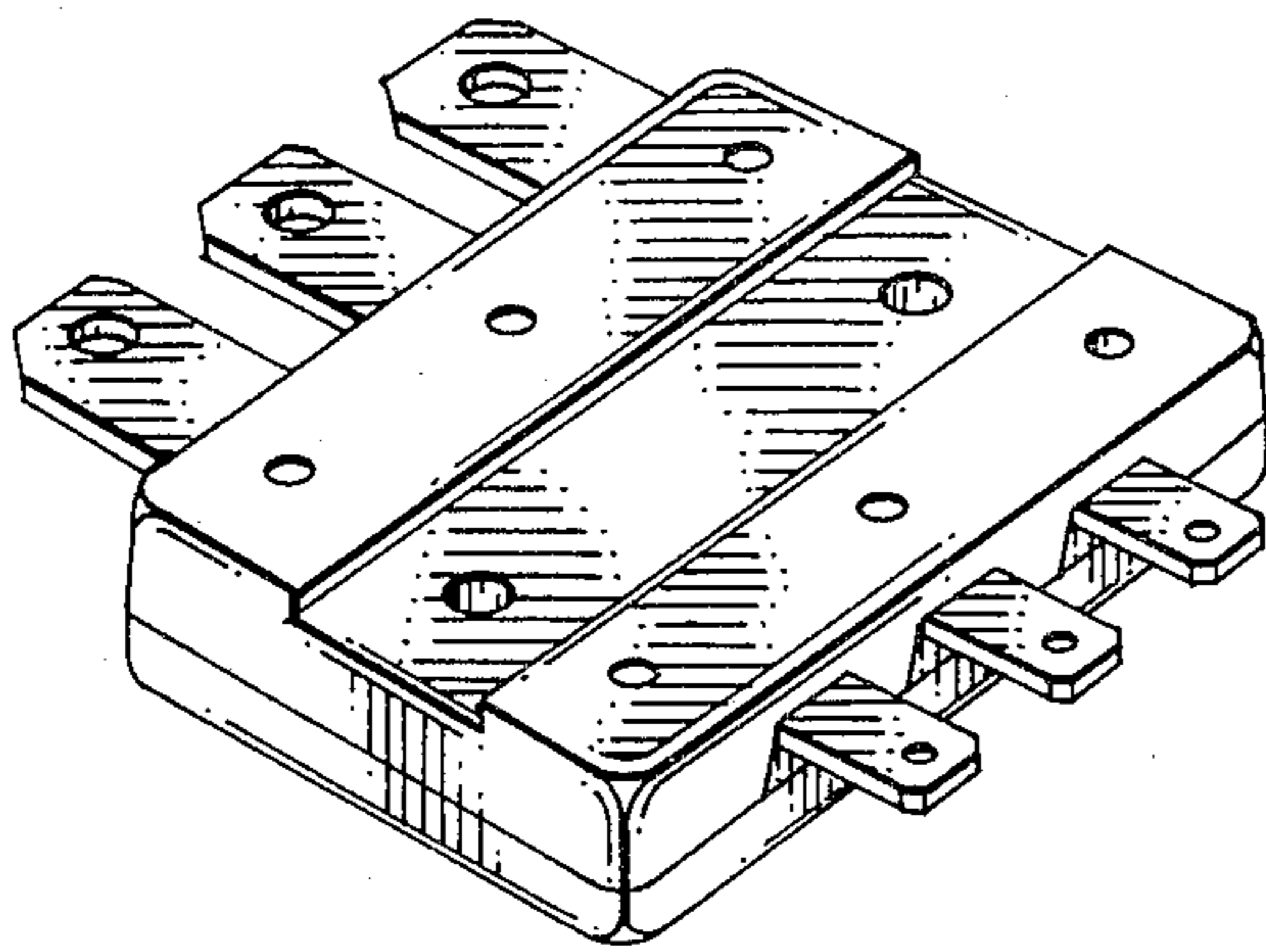


FIG. 1

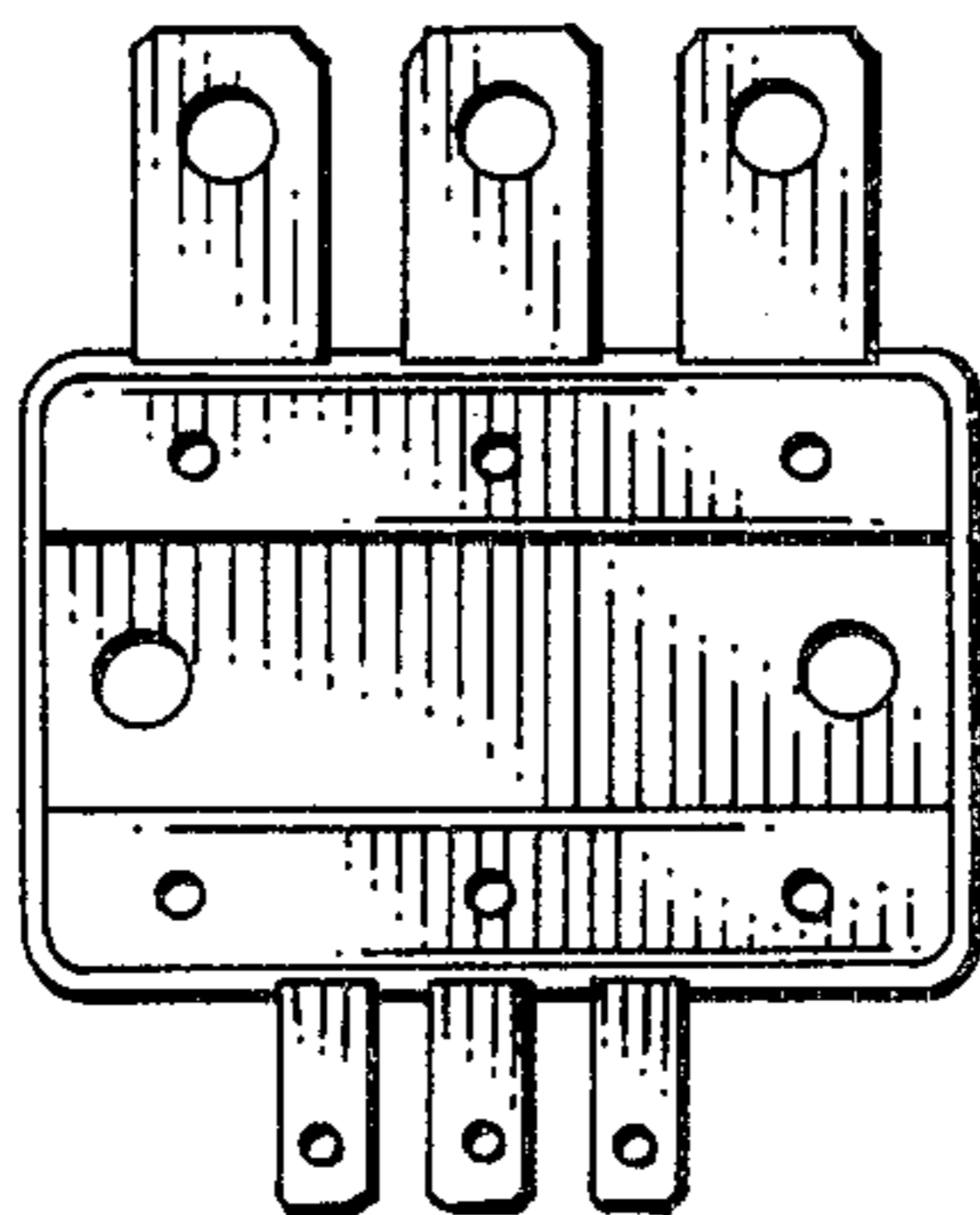


FIG. 2

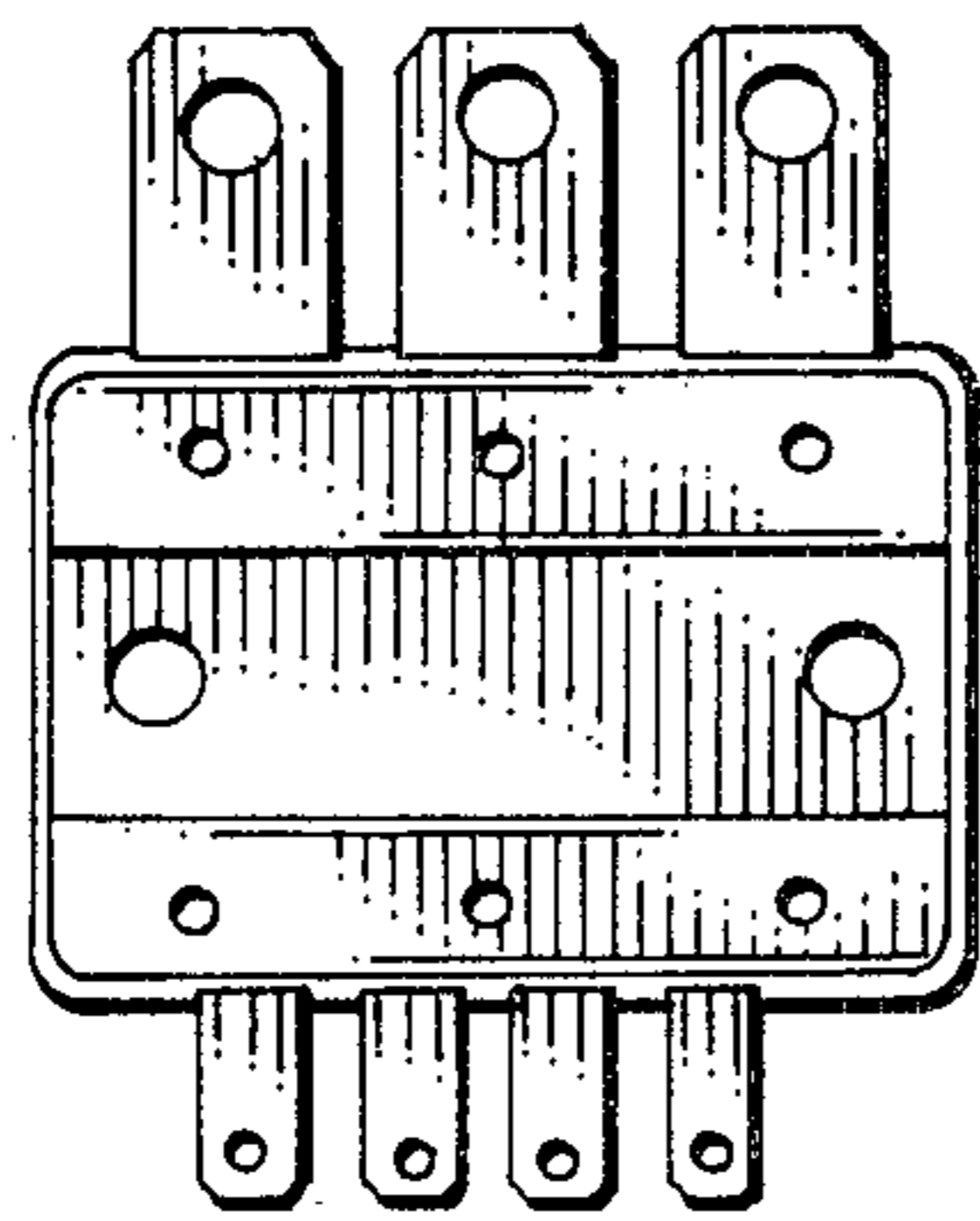


FIG. 8

FIG. 4

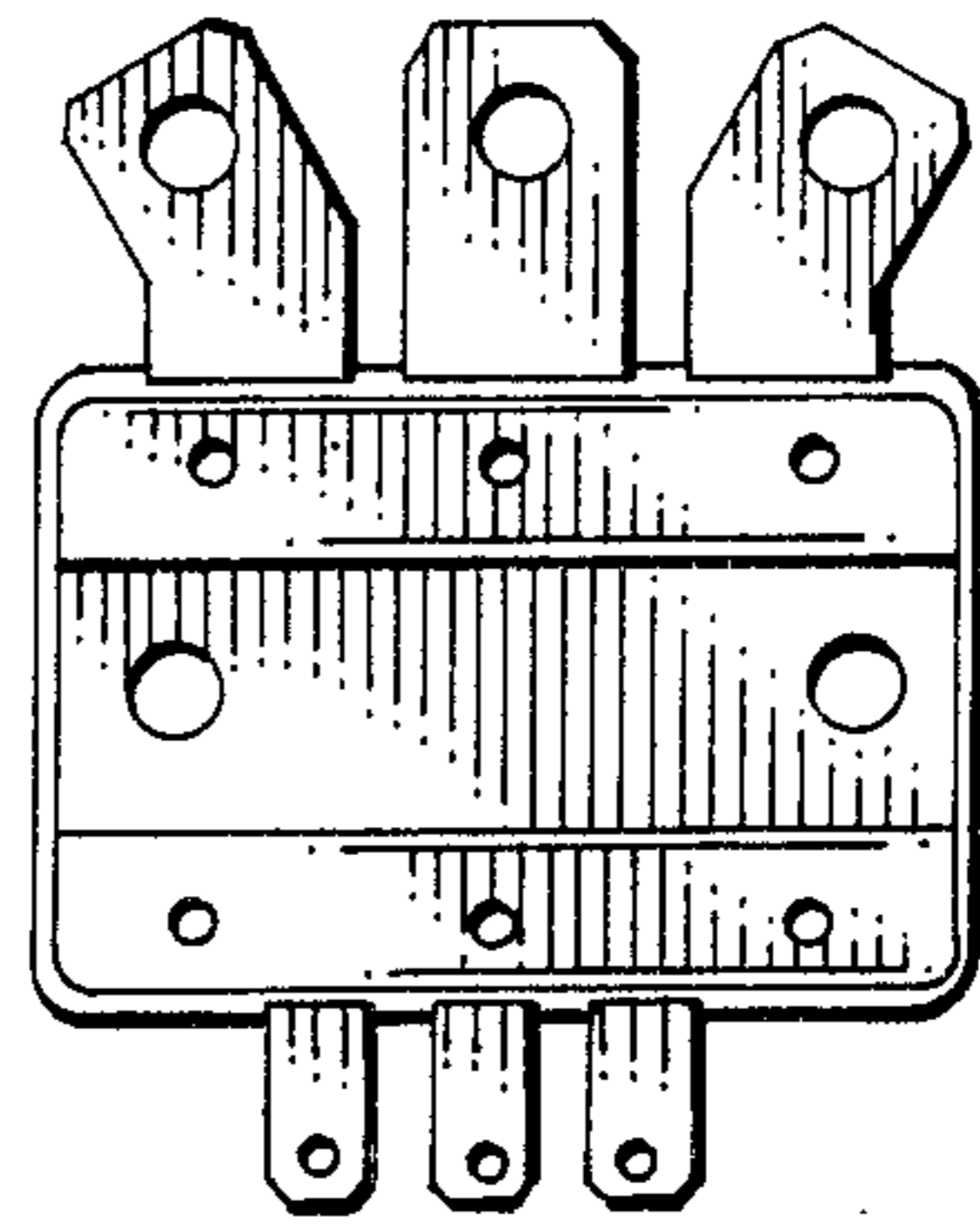


FIG. 10

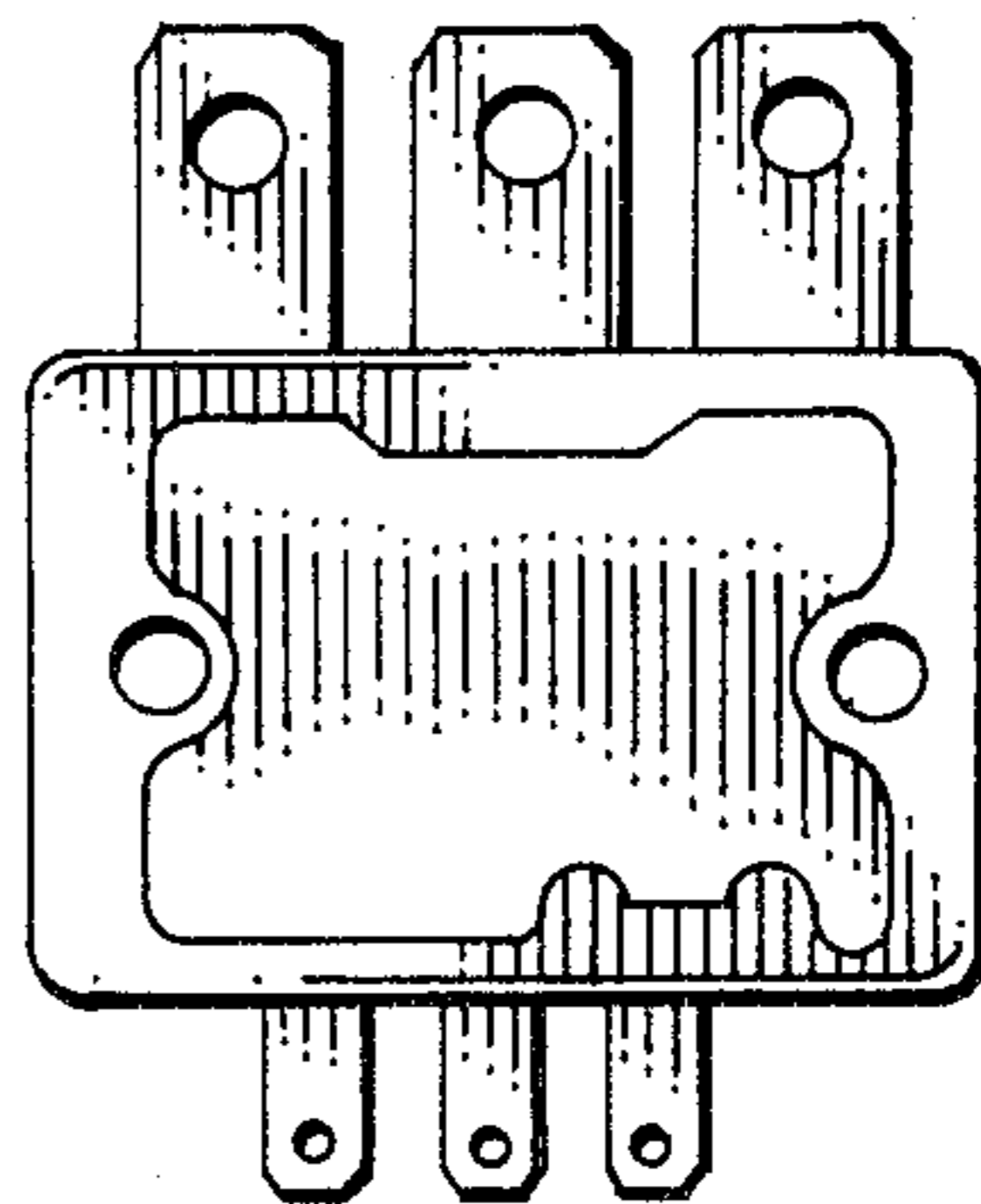


FIG. 3

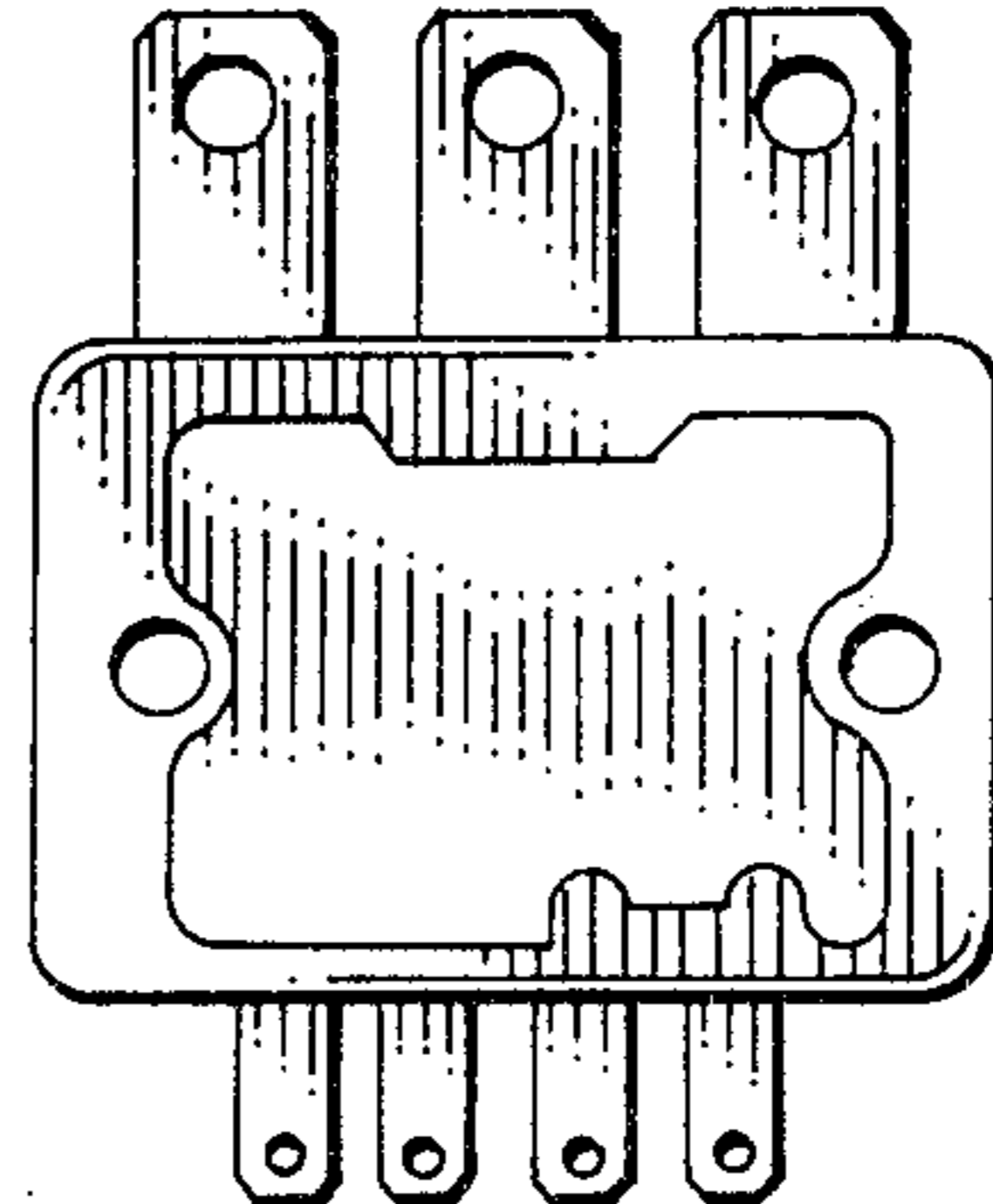


FIG. 9



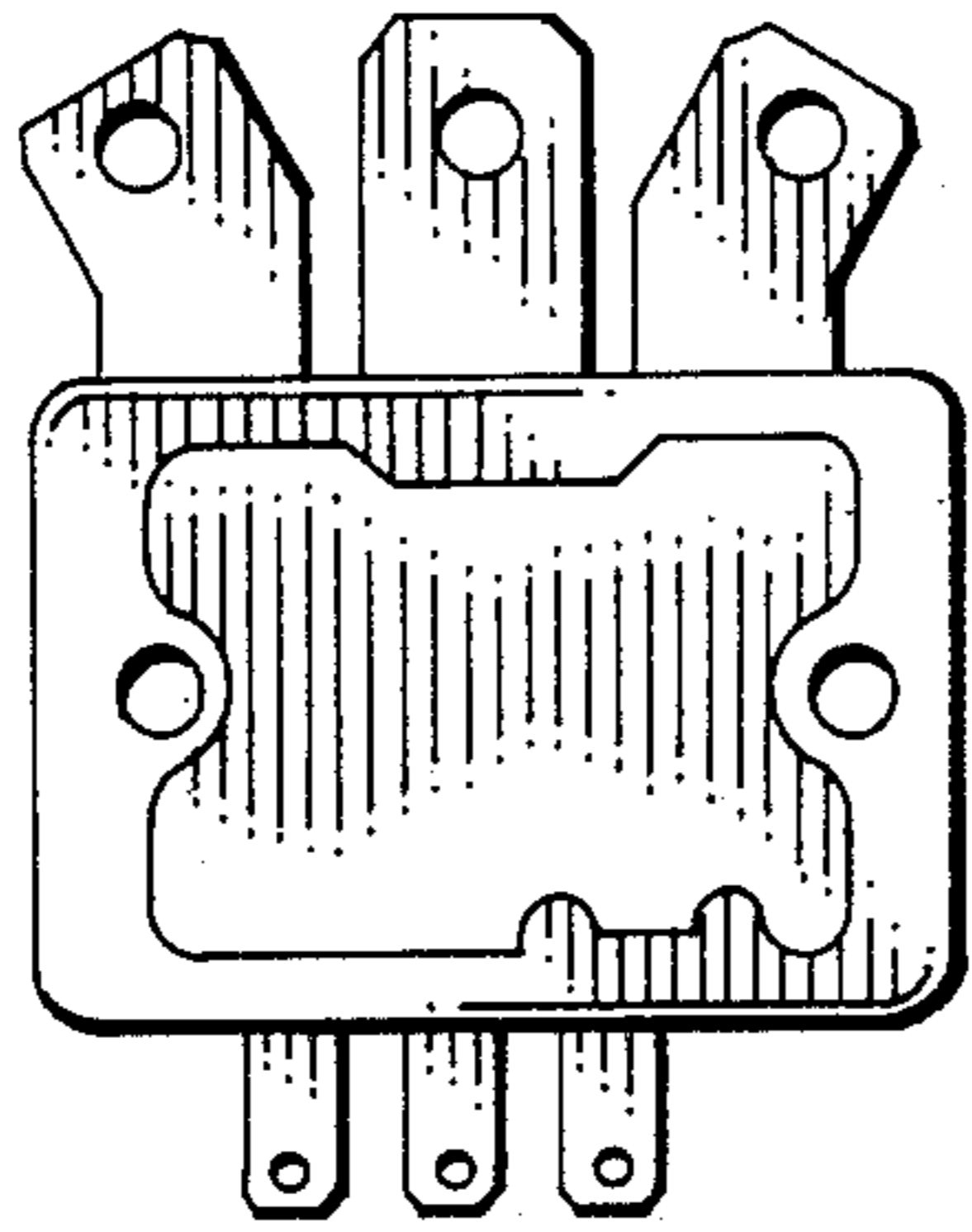


FIG. 11

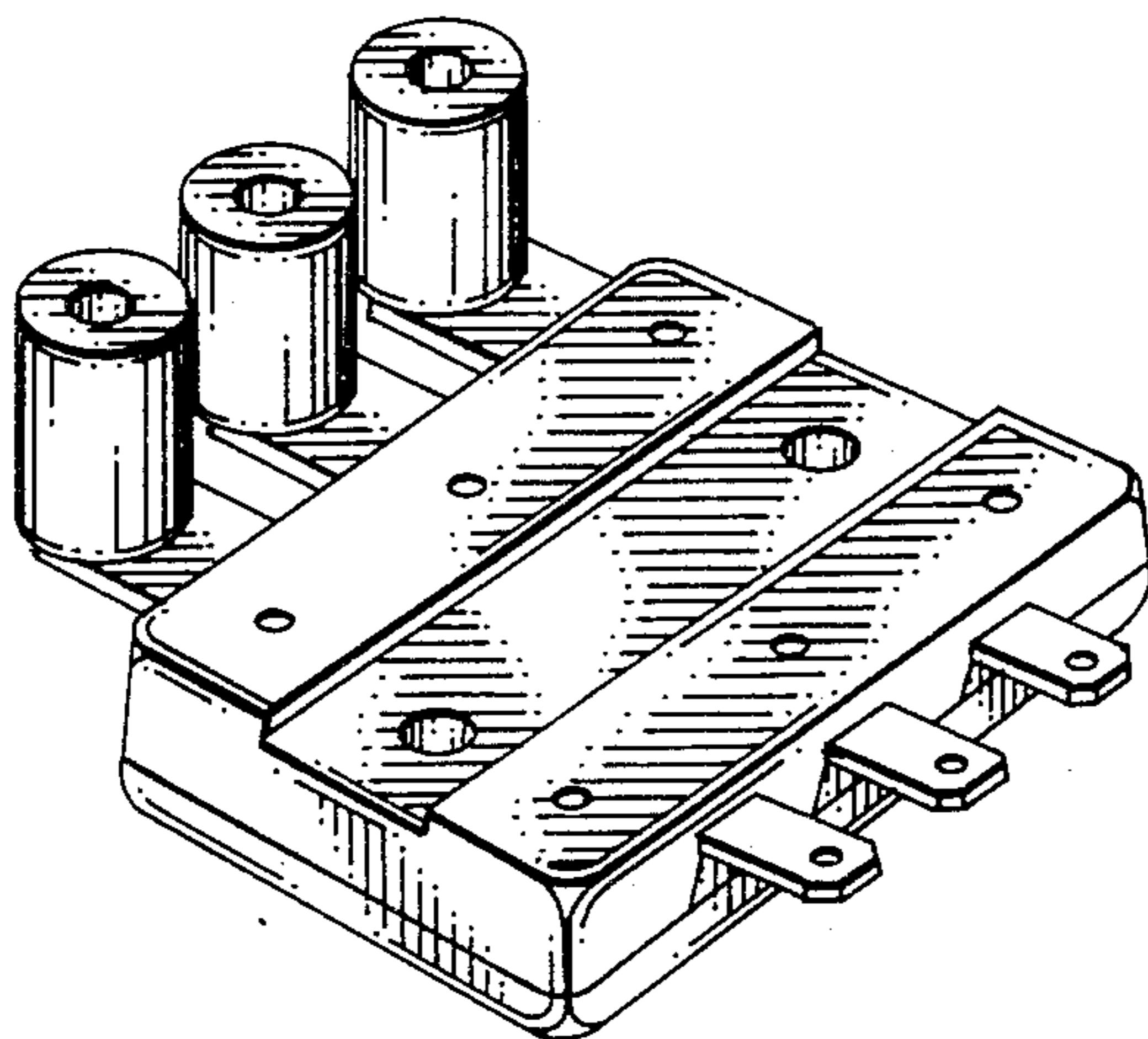


FIG. 12

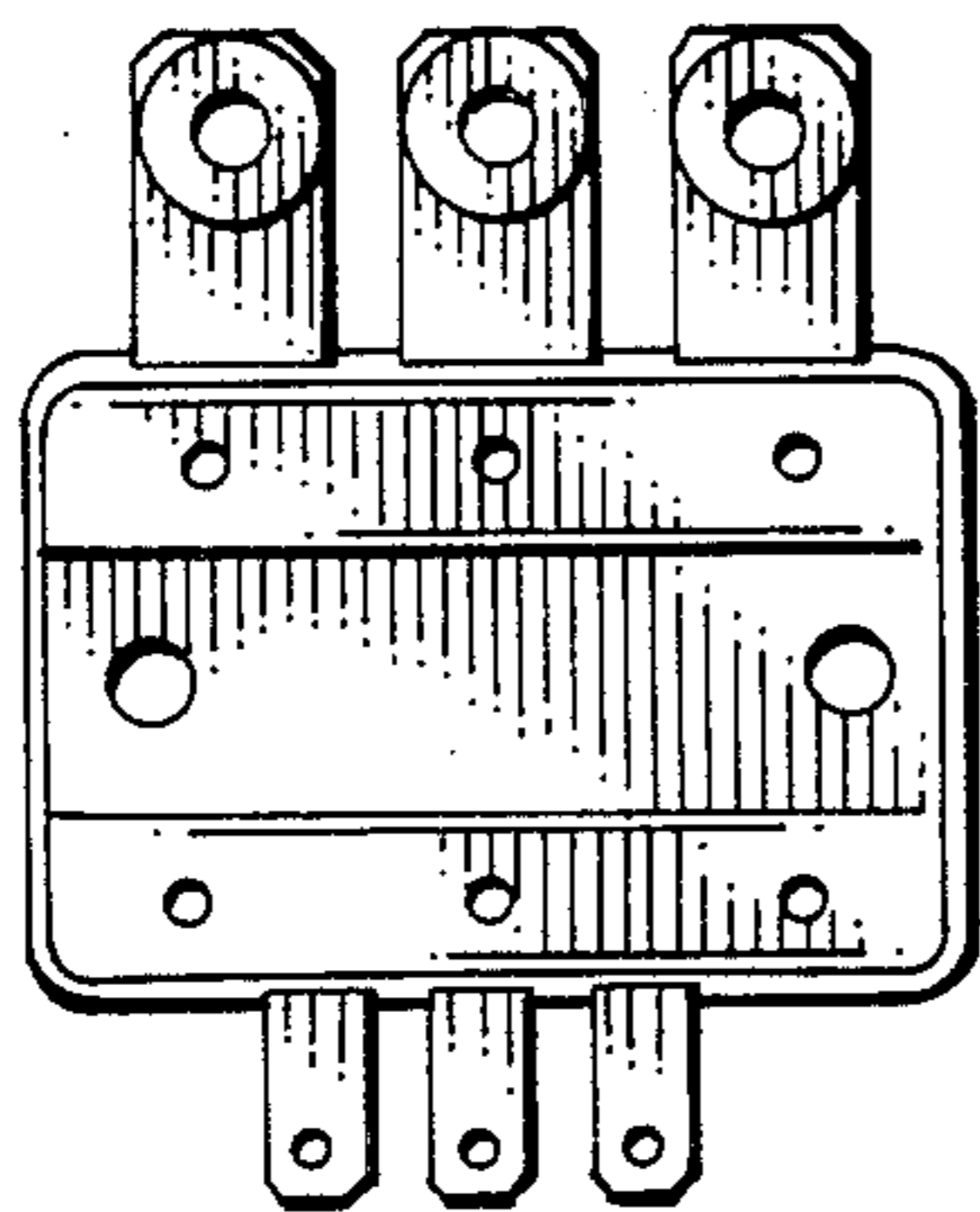


FIG. 13



FIG. 5



FIG. 6



FIG. 14

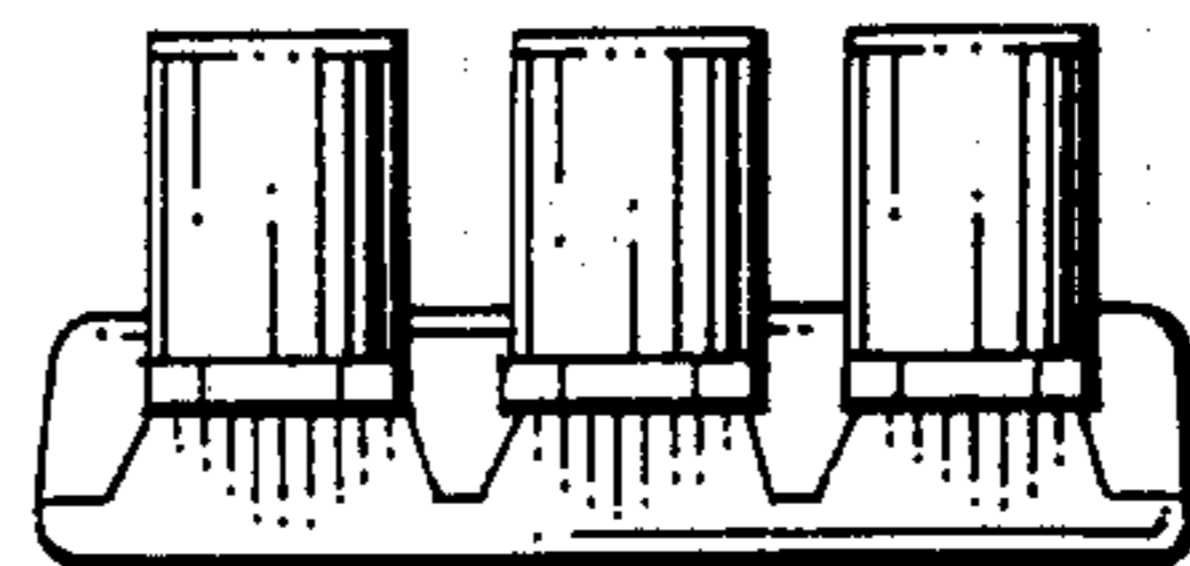


FIG. 15



FIG. 7

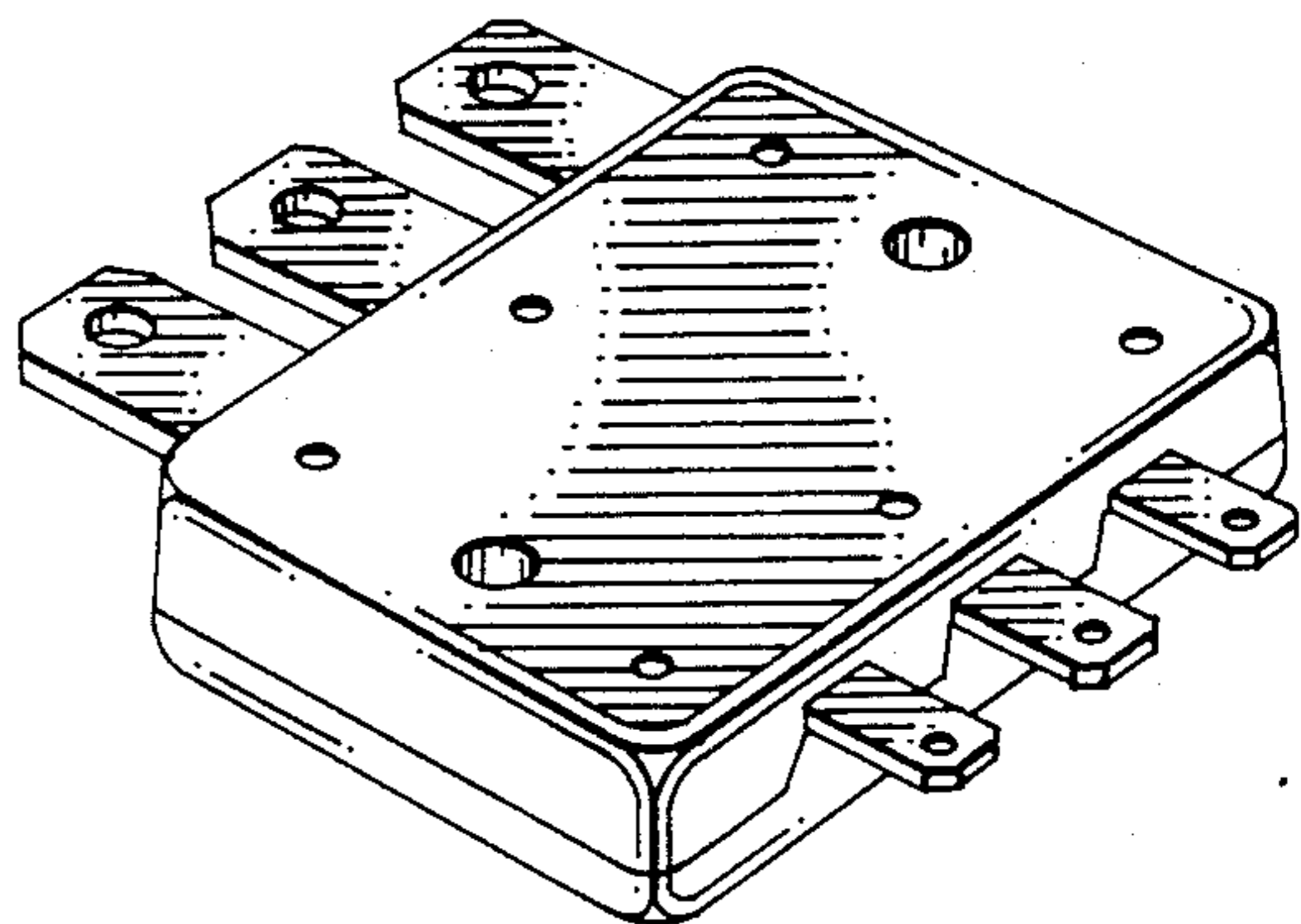


FIG. 16

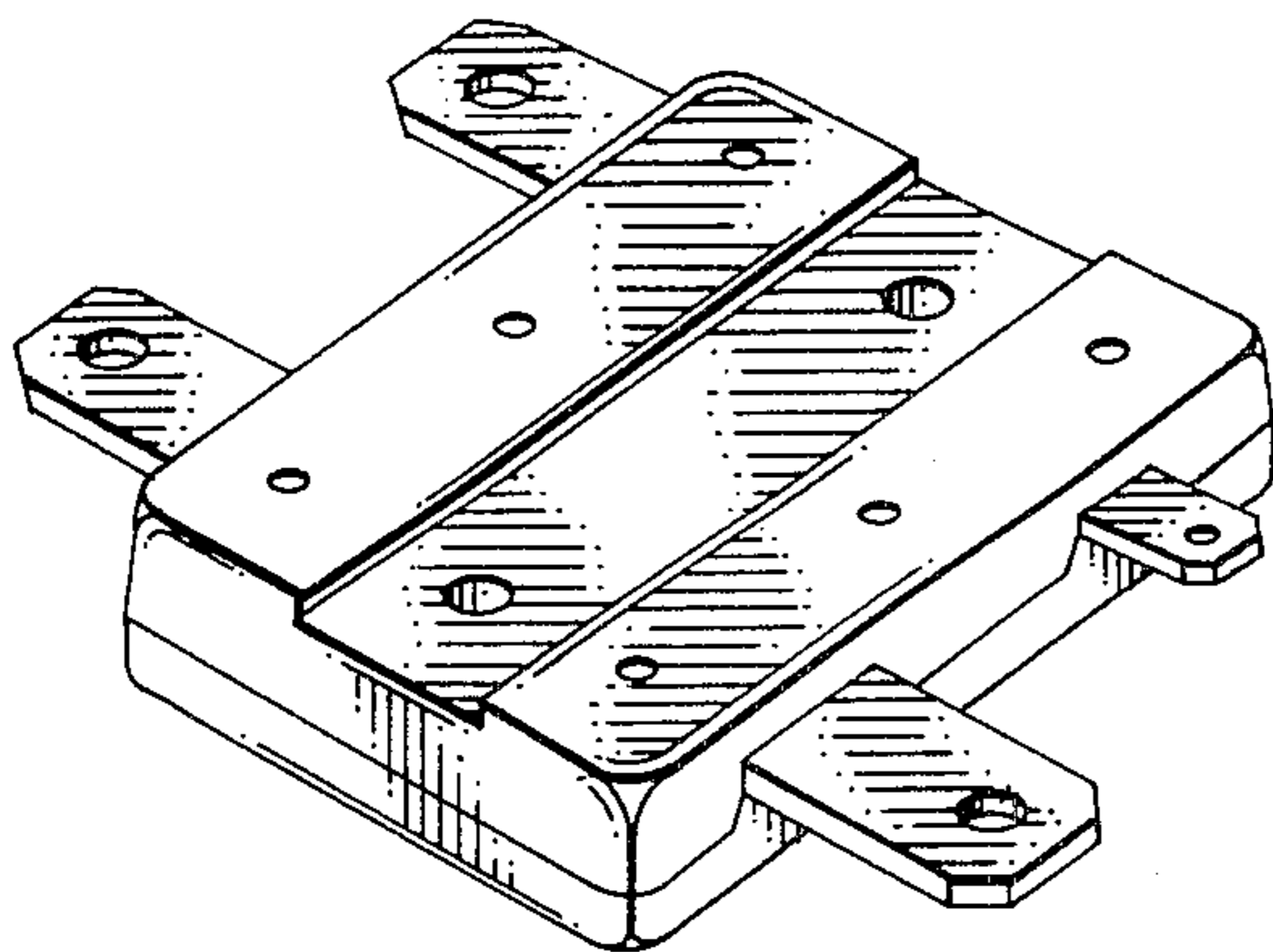


FIG. 17

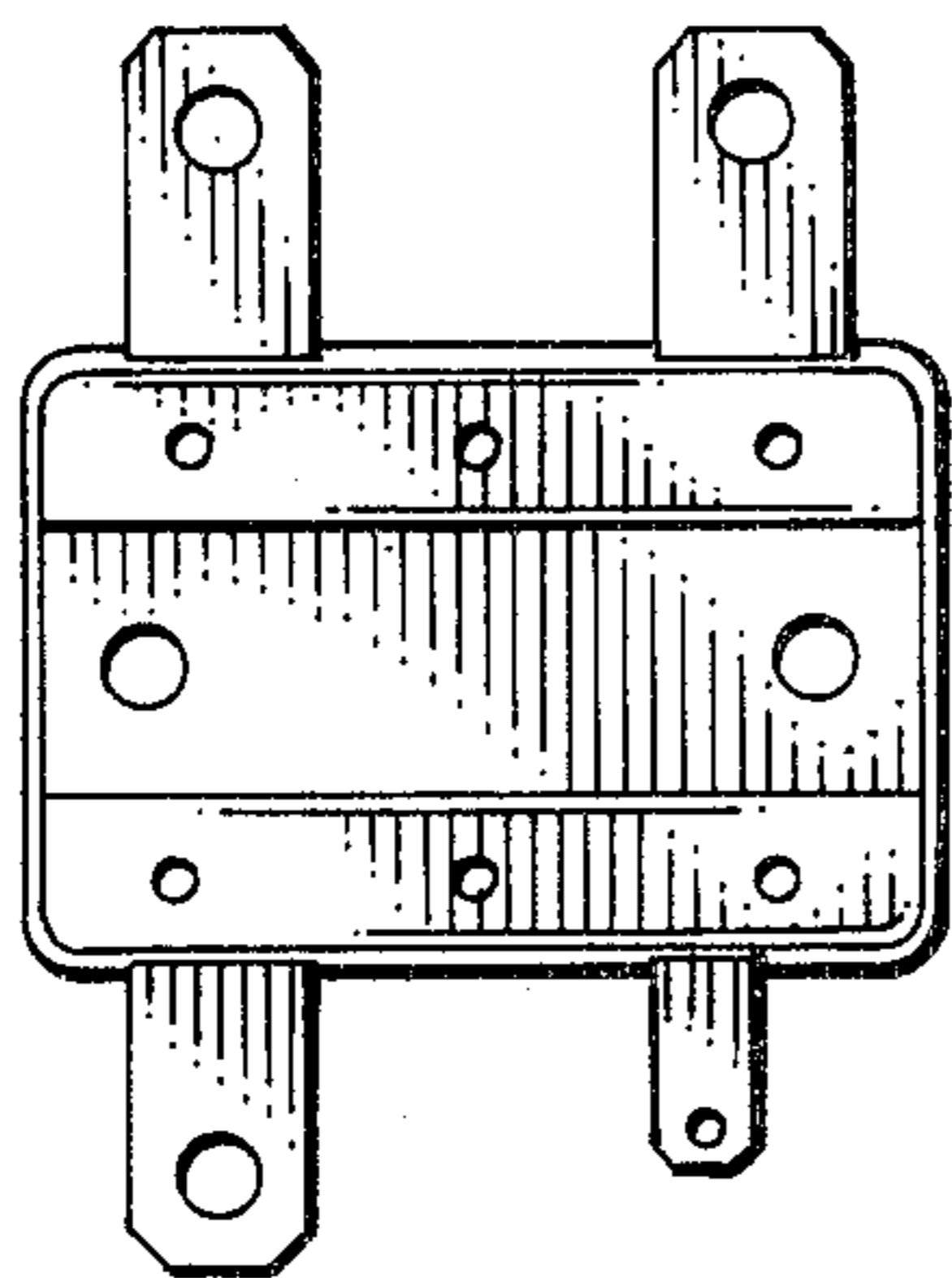


FIG. 18

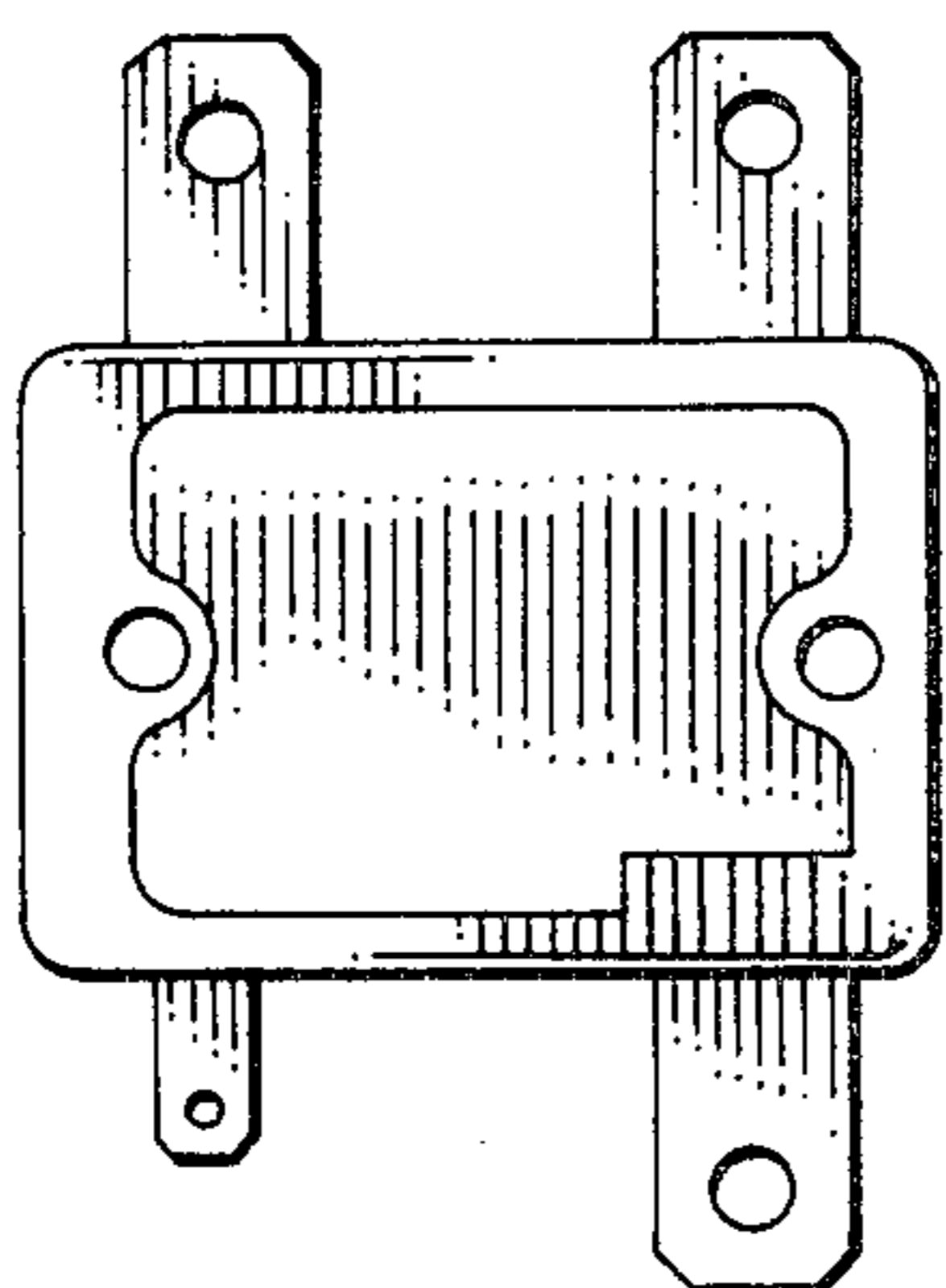


FIG. 19

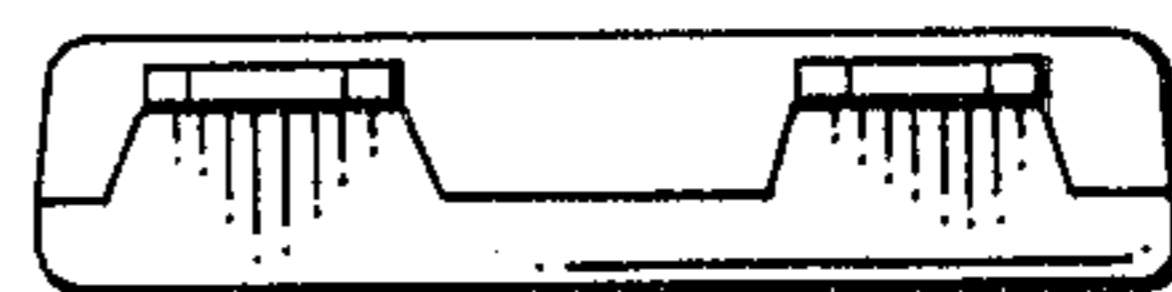


FIG. 20

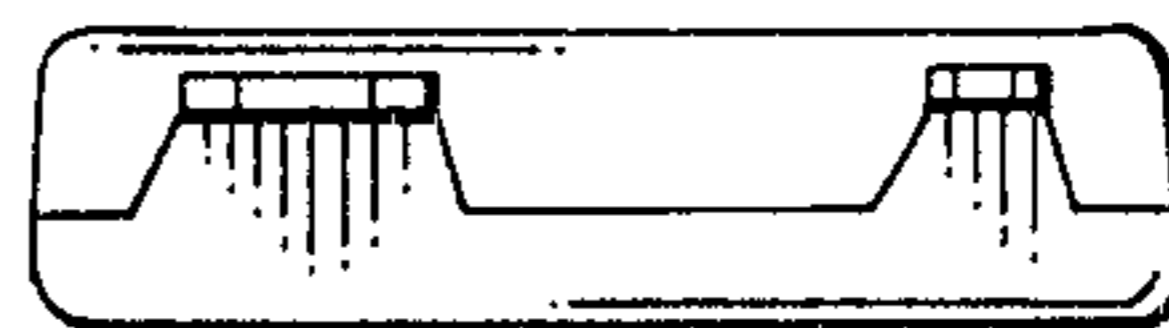


FIG. 21